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Ching-Hsiang CHENG; Chen CHAO; Yin-Nee CHEUNG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 01/01/2008; 01/04/2008; 01/02/2008

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

2. Name and address of receiving party(ies)

Name: The Hong Kong Polytechnic University

Internal Address: Hung Hom, Kowloon, Hong Kong

Street Address: Hung Hom, Kowloon, Hong Kong

City: Kowloon

State:

Country: Hong Kong

Zip:

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4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

12/007,610

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: The Hong Kong Polytechnic University

Internal Address:

Street Address: 1800 Diagonal Road, Suite 600

Mailbox#119

City: Alexandria

State: Virginia Zip: 22314

Phone Number: 703-647-6569

Fax Number: 703-647-6009

Email Address: pdmaquit@inet.polyu.edu.hk

6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40

- ☐ Authorized to be charged to deposit account  
☒ Enclosed  
☐ None required (government interest not affecting title)

8. Payment information

Deposit Account Number

Authorized User Name

9. Signature:

Signature

Date

Dr. Sun-wing LU

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

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Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

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# ASSIGNMENT

In consideration of One Dollar and other good and valuable consideration, of which receipt is acknowledged, I Ching-Hsiang CHENG of The Hong Kong Polytechnic University, sell and assign to The Hong Kong Polytechnic University, a Hong Kong entity, the entire right, title, and interest in and to the invention titled Fluidic Piezoresistive Strain Gauge (IP-447A) invented by me as described in the application for United States patent executed by me concurrently herewith, and any and all applications for patent and patents in any and all countries, including all divisions, continuations, reissues, and extensions thereof and all rights of priority resulting from the filing of said United States application and authorize and request any official whose duty it is to issue patents to issue any patent on said improvements or resulting therefrom to said The Hong Kong Polytechnic University, or its successors, assigns, or nominees and agree that on request and without further consideration, but at the expense of The Hong Kong Polytechnic University, I will communicate to the University or its representatives or nominees any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally aid said University, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention in all countries.

Ching-Hsiang Cheng, this 1<sup>st</sup> day of JAN 2008

## ASSIGNMENT

In consideration of One Dollar and other good and valuable consideration, of which receipt is acknowledged, I Chen CHAO of The Hong Kong Polytechnic University, sell and assign to The Hong Kong Polytechnic University, a Hong Kong entity, the entire right, title, and interest in and to the invention titled Fluidic Piezoresistive Strain Gauge (IP-447A) invented by me as described in the application for United States patent executed by me concurrently herewith, and any and all applications for patent and patents in any and all countries, including all divisions, continuations, reissues, and extensions thereof and all rights of priority resulting from the filing of said United States application and authorize and request any official whose duty it is to issue patents to issue any patent on said improvements or resulting therefrom to said The Hong Kong Polytechnic University, or its successors, assigns, or nominees and agree that on request and without further consideration, but at the expense of The Hong Kong Polytechnic University, I will communicate to the University or its representatives or nominees any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally aid said University, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention in all countries.



, this 4th day of JAN 2008

## ASSIGNMENT

In consideration of One Dollar and other good and valuable consideration, of which receipt is acknowledged, I Yin-Nee CHEUNG of The Hong Kong Polytechnic University, sell and assign to The Hong Kong Polytechnic University, a Hong Kong entity, the entire right, title, and interest in and to the invention titled Fluidic Piezoresistive Strain Gauge (IP-447A) invented by me as described in the application for United States patent executed by me concurrently herewith, and any and all applications for patent and patents in any and all countries, including all divisions, continuations, reissues, and extensions thereof and all rights of priority resulting from the filing of said United States application and authorize and request any official whose duty it is to issue patents to issue any patent on said improvements or resulting therefrom to said The Hong Kong Polytechnic University, or its successors, assigns, or nominees and agree that on request and without further consideration, but at the expense of The Hong Kong Polytechnic University, I will communicate to the University or its representatives or nominees any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally aid said University, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention in all countries.

Cheng Yin Nee, this 22 day of JAN 2008